

In the Claims:

1. (currently amended) A die used for sealing and molding an electronic component with a resin material, said die comprising:

a fixed die;

a movable die arranged opposite to the fixed die;

upper and lower cavities provided in said fixed die and said movable die in respective die planes thereof to face each other along a parting-line plane of said fixed die and said movable die, for molding the resin material;

a concavity receiving and setting a support having the electronic component mounted thereto;

a pot arranged at one of said fixed die and said movable die for supplying the resin material;

a plunger fit internal to said pot for applying pressure to the resin material; and

a resin channel to allow said pot and said upper cavity to communicate with each other for transporting the resin material in the melted state;

and

having a coating layer consisting of a nickel-tungsten alloy on at least a surface thereof contacting the resin material in a melted state when the resin material is molded, wherein said at least a surface includes an internal surface of said upper and lower cavities, an internal surface of said resin channel, an internal surface of said concavity, an internal surface of said pot, said

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27 parting-line plane of each of said fixed die and said  
28 movable die, and an external surface of said plunger;

29 wherein said coating layer is a plating layer formed  
30 of said nickel-tungsten alloy, which contains more than 20%  
31 by weight and less than 44% by weight of tungsten.

Claims 2 and 3 (canceled).

1 4. (original) The die of claim 1, wherein said coating layer  
2 is 1  $\mu$ m to 20  $\mu$ m in thickness.

Claim 5 (canceled).

1 6. (currently amended) The die of ~~claim 5~~, claim 1, further  
2 comprising an ejector pin ejecting and releasing from said  
3 upper and lower cavities a resin-molded body molded in said  
4 upper and lower cavities, and an ejector pin fitting hole  
5 fitting said ejector pin therein, wherein said ejector pin  
6 has an external surface further provided with said coating  
7 layer and/or said ejector pin fitting hole has an internal  
8 surface further provided with said coating layer.

1 7. (currently amended) The die of ~~claim 5~~, claim 1, wherein  
2 said resin channel includes a cull and a runner and gate  
3 arranged opposite to said pot for dispensing the resin  
4 material in the melted state, said cull and said runner and  
5 gate having an internal surface further provided with said  
6 coating layer.

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1 8. (currently amended) The die of ~~claim 5~~, claim 1, further  
2 comprising an air vent allowing said upper cavity to  
3 communicate external to the die, said air vent having a  
4 surface further provided with said coating layer.

1 9. (previously presented) The die of claim 1, wherein said  
2 nickel-tungsten alloy contains at most 40% by weight of  
3 said tungsten.

Claims 10 and 11 (canceled).

1 12. (previously presented) A die arrangement used for sealing  
2 and molding an electronic component with a resin material,  
3 said die arrangement comprising:  
4 a fixed die;  
5 a movable die arranged opposite to the fixed die;  
6 upper and lower cavities provided in said fixed die  
7 and said movable die in respective die planes thereof to  
8 face each other along a parting-line plane of said fixed  
9 die and said movable die, for molding the resin material;  
10 a concavity receiving and setting a support having the  
11 electronic component mounted thereto;  
12 a pot arranged at one of said fixed die and said  
13 movable die for supplying the resin material;  
14 a plunger fit internal to said pot for applying  
15 pressure to the resin material;

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16 a resin channel to allow said pot and said upper  
17 cavity to communicate with each other for transporting the  
18 resin material in the melted state; and

19 a coating layer of a nickel-tungsten alloy that is  
20 provided on surfaces of said die arrangement contacting the  
21 resin material in a melted state when the resin material is  
22 molded, wherein said surfaces include an internal surface  
23 of said upper and lower cavities, an internal surface of  
24 said resin channel, an internal surface of said concavity,  
25 an internal surface of said pot, said parting-line plane of  
26 each of said fixed die and said movable die, and an  
27 external surface of said plunger, and wherein said coating  
28 layer is a plating layer formed of said nickel-tungsten  
29 alloy, which contains at least 20% by weight and at most  
30 60% by weight of tungsten.

1 13. (previously presented) The die of claim 12, further  
2 comprising an ejector pin ejecting and releasing from said  
3 upper and lower cavities a resin-molded body molded in said  
4 upper and lower cavities, and an ejector pin fitting hole  
5 fitting said ejector pin therein, wherein said ejector pin  
6 has an external surface provided with said coating layer  
7 and/or said ejector pin fitting hole has an internal  
8 surface provided with said coating layer.

1 14. (previously presented) The die of claim 12, wherein said  
2 resin channel includes a cull and a runner and gate  
3 arranged opposite to said pot for dispensing the resin

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4 material in the melted state, said cull and said runner and  
5 gate having an internal surface provided with said coating  
6 layer.

1 15. (previously presented) The die of claim 12, further  
2 comprising an air vent allowing said upper cavity to  
3 communicate external to the die, said air vent having a  
4 surface provided with said coating layer.

Claims 16 to 19 (canceled).

1 20. (previously presented) The die of claim 9, wherein said  
2 coating layer has a thickness of 1  $\mu\text{m}$  to 20  $\mu\text{m}$ .

Claims 21 and 22 (canceled).

[RESPONSE CONTINUES ON NEXT PAGE]

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